



MS ISSUE FEE
PATENT
3313-1099P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: CHANG, Shu-Ming et al. Conf.: 2341
Appl. No.: 10/765,961 Group: 2815
Filed: January 29, 2004 Examiner: Sheila V. Clark
For: WAFER LEVEL CHIP SCALE PACKAGING STRUCTURE
AND METHOD OF FABRICATING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.312

HANDCARRY TO:
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March 11, 2005

Sir:

Pursuant to the provisions of 37 C.F.R. § 1.312, the following amendments and remarks are respectfully submitted in connection with the above-identified application. It is respectfully requested that the following amendments be entered without withdrawing the application from issue.

This amendment includes:

Amended Claim Set; and

Remarks.

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